



FETek Technology Corp.

FKBB3115E

P-Ch 30V Fast Switching MOSFETs



## Features

- ★ Advanced Trench MOS Technology
- ★ ESD Protection
- ★ 100% EAS Guaranteed
- ★ Reliable and Rugged
- ★ Green Device Available

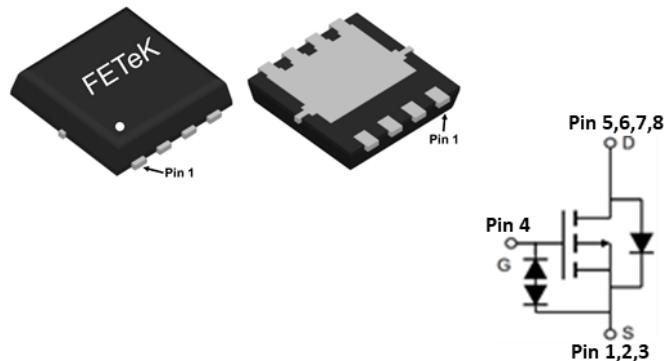
## Product Summary

BVDSS	RDS(ON)	ID
-30V	8.5mΩ	-32A

## Applications

- ★ Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.

## PRPAK3X3 Pin Configuration



## Absolute Maximum Ratings

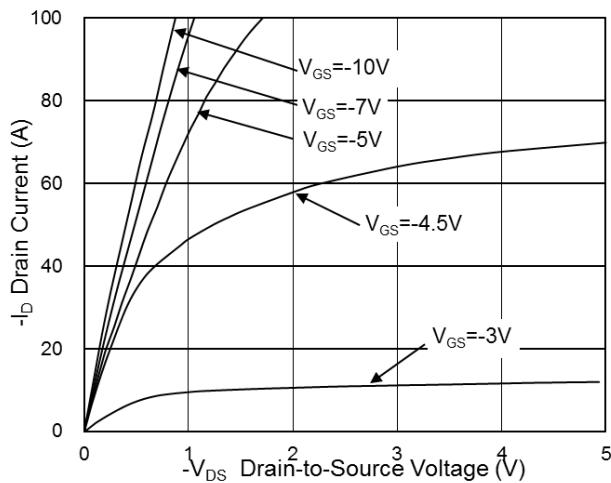
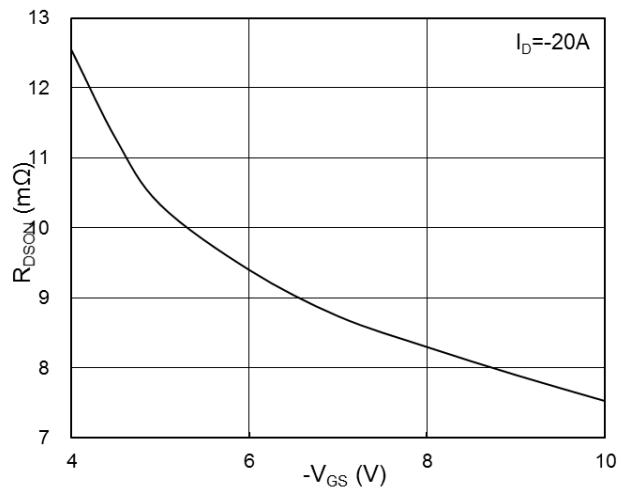
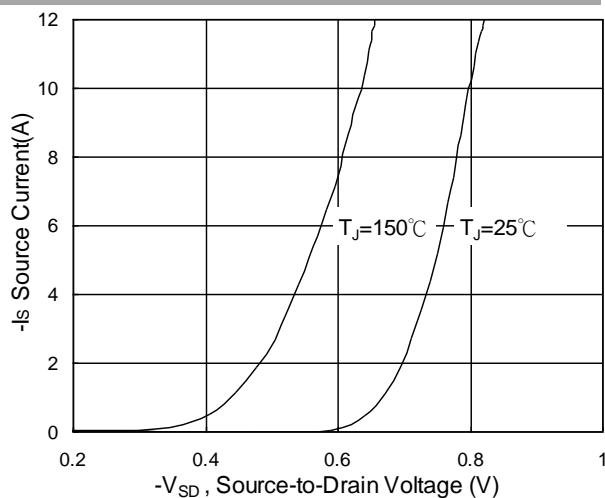
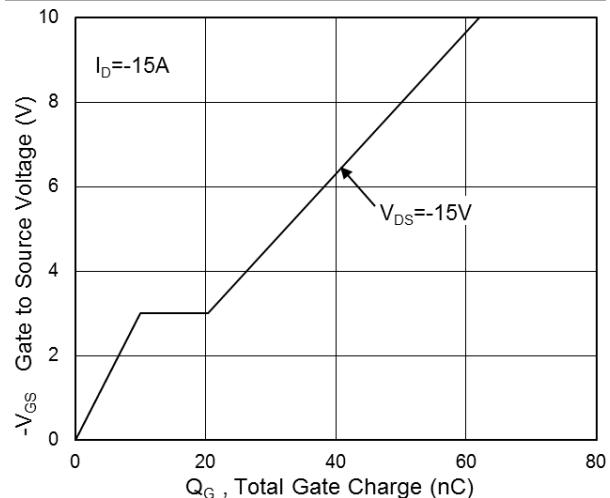
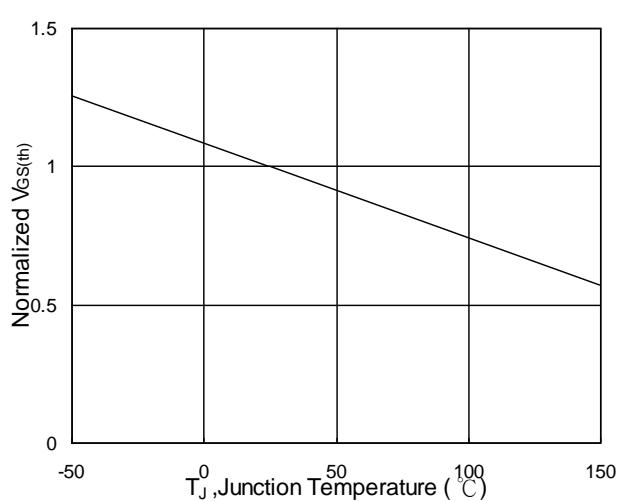
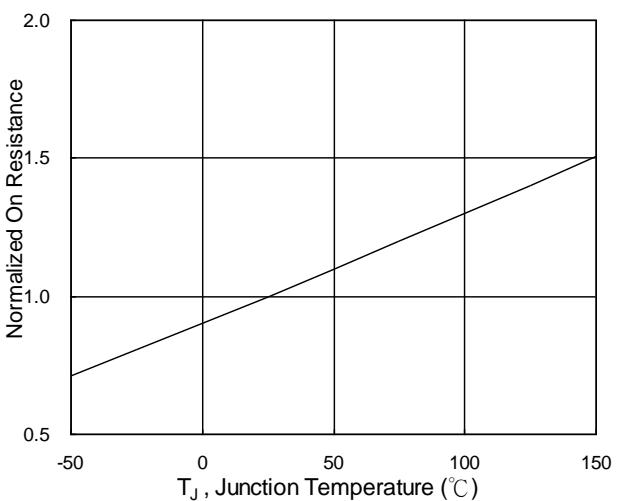
Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current <sup>1,6</sup>	-32	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current <sup>1,6</sup>	-25	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-128	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	125	mJ
$I_{AS}$	Avalanche Current	-50	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation <sup>4</sup>	96	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

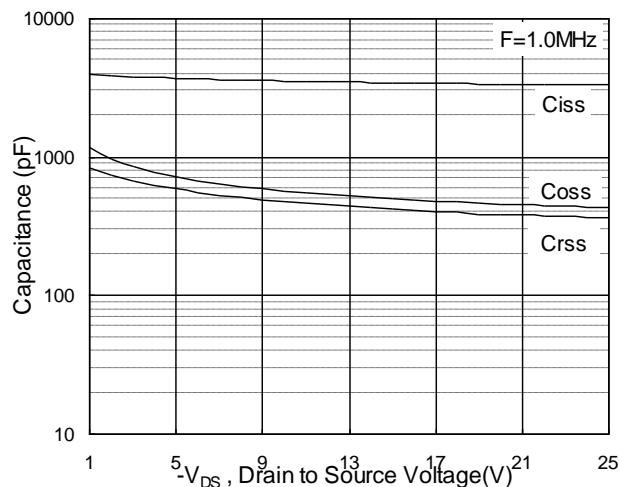
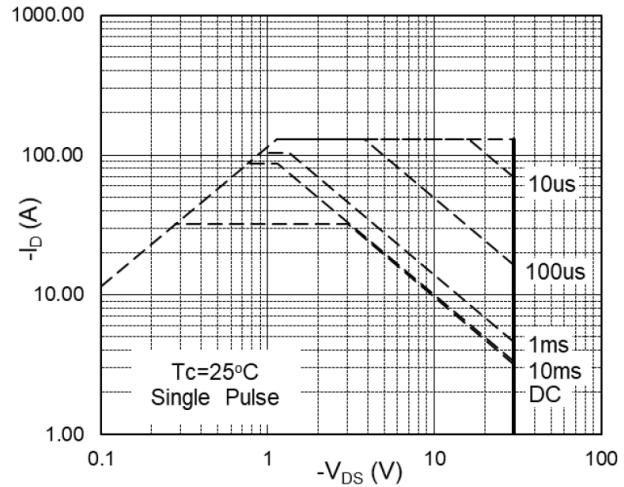
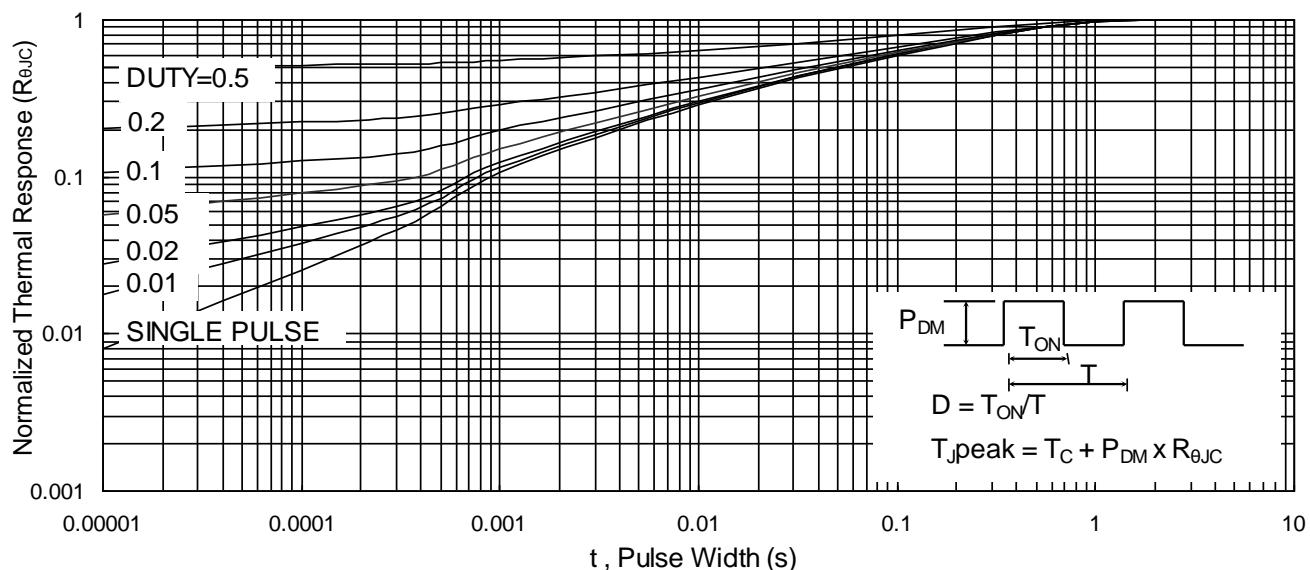
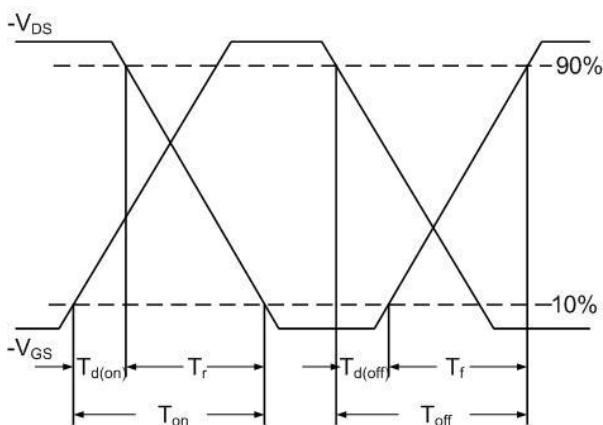
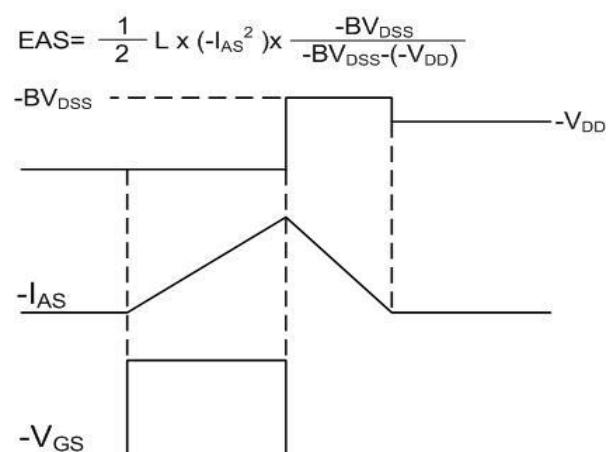
## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	75	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	1.3	°C/W



### Typical Characteristics


**Fig.1 Typical Output Characteristics**

**Fig.2 On-Resistance vs G-S Voltage**

**Fig.3 Source Drain Forward Characteristics**

**Fig.4 Gate-Charge Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$** 

**Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$**


**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Switching Waveform**